

HEXFET® Power MOSFET

**Applications**

- Synchronous Rectification
- Active ORing

| $V_{DSS}$ | $R_{DS(on)}$ max | $I_D$             |
|-----------|------------------|-------------------|
| 30V       | 0.0028 $\Omega$  | 210A <sup>⑥</sup> |

**Benefits**

- Ultra Low On-Resistance
- Low Gate Impedance to Reduce Switching Losses
- Fully Avalanche Rated



**Absolute Maximum Ratings**

|                                   | Parameter                                | Max.             | Units               |
|-----------------------------------|------------------------------------------|------------------|---------------------|
| $I_D$ @ $T_C = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS}$ @ 10V | 210 <sup>⑥</sup> | A                   |
| $I_D$ @ $T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS}$ @ 10V | 100 <sup>⑥</sup> |                     |
| $I_{DM}$                          | Pulsed Drain Current <sup>①</sup>        | 1000             |                     |
| $P_D$ @ $T_C = 25^\circ\text{C}$  | Power Dissipation                        | 230              | W                   |
| $P_D$ @ $T_A = 25^\circ\text{C}$  | Power Dissipation                        | 3.8              |                     |
|                                   | Linear Derating Factor                   | 1.5              | W/ $^\circ\text{C}$ |
| $V_{GS}$                          | Gate-to-Source Voltage                   | $\pm 20$         | V                   |
| dv/dt                             | Peak Diode Recovery dv/dt <sup>③</sup>   | 5.0              | V/ns                |
| $T_J, T_{STG}$                    | Junction and Storage Temperature Range   | -55 to + 175     | $^\circ\text{C}$    |

**Thermal Resistance**

|                 | Parameter                           | Typ. | Max. | Units              |
|-----------------|-------------------------------------|------|------|--------------------|
| $R_{\theta JC}$ | Junction-to-Case                    | —    | 0.65 | $^\circ\text{C/W}$ |
| $R_{\theta CS}$ | Case-to-Sink, Flat, Greased Surface | 0.24 | —    |                    |
| $R_{\theta JA}$ | Junction-to-Ambient                 | —    | 40   |                    |

**Typical SMPS Topologies**

- Forward and Bridge Converters with Synchronous Rectification for Telecom and Industrial Applications
- Offline High Power AC/DC Convertors using Synchronous Rectification

Notes <sup>①</sup> through <sup>⑥</sup> are on page 8

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## Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

|                                 | Parameter                            | Min. | Typ.  | Max. | Units               | Conditions                                           |
|---------------------------------|--------------------------------------|------|-------|------|---------------------|------------------------------------------------------|
| $V_{(BR)DSS}$                   | Drain-to-Source Breakdown Voltage    | 30   | —     | —    | V                   | $V_{GS} = 0V, I_D = 250\mu A$                        |
| $\Delta V_{(BR)DSS}/\Delta T_J$ | Breakdown Voltage Temp. Coefficient  | —    | 0.028 | —    | V/ $^\circ\text{C}$ | Reference to $25^\circ\text{C}$ , $I_D = 1mA$        |
| $R_{DS(on)}$                    | Static Drain-to-Source On-Resistance | —    | 2.3   | 2.8  | $m\Omega$           | $V_{GS} = 10V, I_D = 76A$ ④                          |
|                                 |                                      | —    | 2.8   | 3.9  |                     | $V_{GS} = 7.0V, I_D = 76A$ ④                         |
| $V_{GS(th)}$                    | Gate Threshold Voltage               | 2.0  | —     | 4.0  | V                   | $V_{DS} = V_{GS}, I_D = 250\mu A$                    |
| $I_{DSS}$                       | Drain-to-Source Leakage Current      | —    | —     | 20   | $\mu A$             | $V_{DS} = 24V, V_{GS} = 0V$                          |
|                                 |                                      | —    | —     | 250  |                     | $V_{DS} = 24V, V_{GS} = 0V, T_J = 150^\circ\text{C}$ |
| $I_{GSS}$                       | Gate-to-Source Forward Leakage       | —    | —     | 200  | nA                  | $V_{GS} = 20V$                                       |
|                                 | Gate-to-Source Reverse Leakage       | —    | —     | -200 |                     | $V_{GS} = -20V$                                      |

## Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

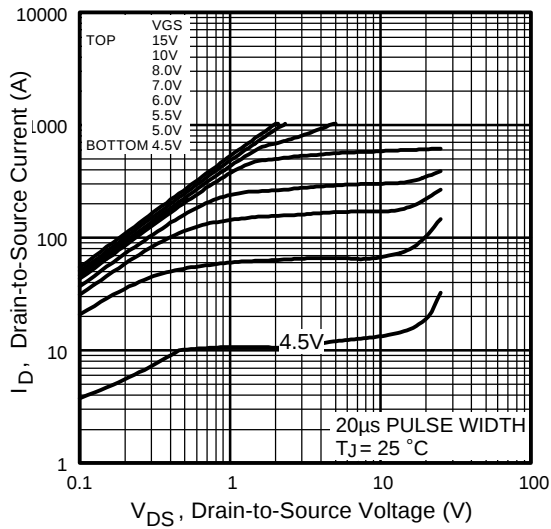
|                        | Parameter                       | Min. | Typ.  | Max. | Units | Conditions                                   |
|------------------------|---------------------------------|------|-------|------|-------|----------------------------------------------|
| $g_{fs}$               | Forward Transconductance        | 150  | —     | —    | S     | $V_{DS} = 24V, I_D = 76A$                    |
| $Q_g$                  | Total Gate Charge               | —    | 209   | —    | nC    | $I_D = 76A$                                  |
| $Q_{gs}$               | Gate-to-Source Charge           | —    | 62    | —    |       | $V_{DS} = 24V$                               |
| $Q_{gd}$               | Gate-to-Drain ("Miller") Charge | —    | 42    | —    |       | $V_{GS} = 10V$ , ④                           |
| $t_{d(on)}$            | Turn-On Delay Time              | —    | 18    | —    | ns    | $V_{DD} = 15V, V_{GS} = 10V$                 |
| $t_r$                  | Rise Time                       | —    | 123   | —    |       | $I_D = 76A$                                  |
| $t_{d(off)}$           | Turn-Off Delay Time             | —    | 53    | —    |       | $R_G = 1.8\Omega$                            |
| $t_f$                  | Fall Time                       | —    | 24    | —    |       | $V_{GS} = 10V$ ④                             |
| $C_{iss}$              | Input Capacitance               | —    | 8250  | —    | pF    | $V_{GS} = 0V$                                |
| $C_{oss}$              | Output Capacitance              | —    | 3000  | —    |       | $V_{DS} = 25V$                               |
| $C_{rss}$              | Reverse Transfer Capacitance    | —    | 290   | —    |       | $f = 1.0MHz$                                 |
| $C_{oss}$              | Output Capacitance              | —    | 10360 | —    |       | $V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$     |
| $C_{oss}$              | Output Capacitance              | —    | 3060  | —    |       | $V_{GS} = 0V, V_{DS} = 24V, f = 1.0MHz$      |
| $C_{oss \text{ eff.}}$ | Effective Output Capacitance    | —    | 2590  | —    |       | $V_{GS} = 0V, V_{DS} = 0V \text{ to } 24V$ ⑤ |

## Avalanche Characteristics

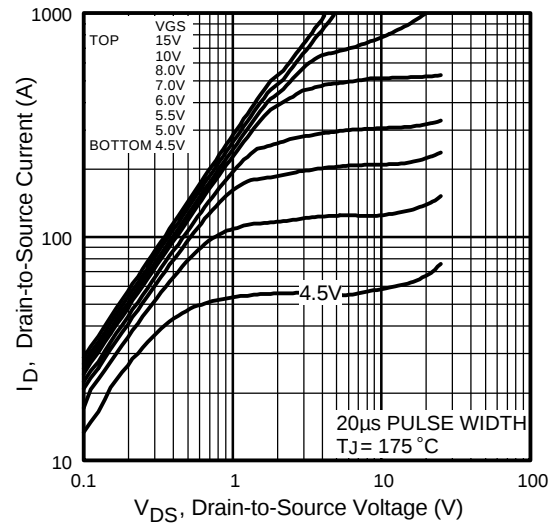
|          | Parameter                      | Typ. | Max. | Units |
|----------|--------------------------------|------|------|-------|
| $E_{AS}$ | Single Pulse Avalanche Energy② | —    | 1700 | mJ    |
| $I_{AR}$ | Avalanche Current①             | —    | 76   | A     |
| $E_{AR}$ | Repetitive Avalanche Energy①   | —    | 23   | mJ    |

## Diode Characteristics

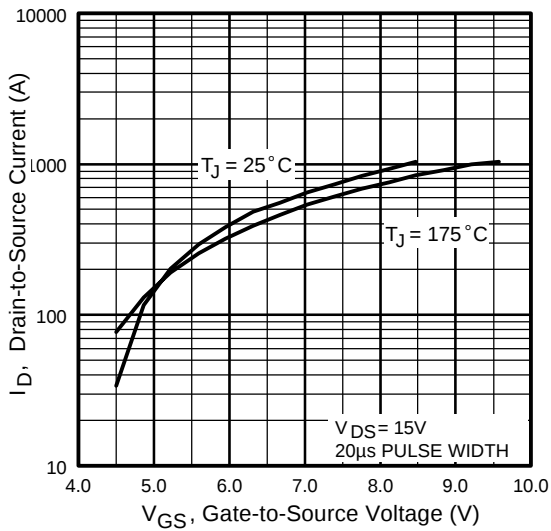
|          | Parameter                              | Min. | Typ. | Max. | Units | Conditions                                                     |
|----------|----------------------------------------|------|------|------|-------|----------------------------------------------------------------|
| $I_S$    | Continuous Source Current (Body Diode) | —    | —    | 210⑥ | A     | MOSFET symbol showing the integral reverse p-n junction diode. |
| $I_{SM}$ | Pulsed Source Current (Body Diode) ①   | —    | —    | 1000 |       |                                                                |
| $V_{SD}$ | Diode Forward Voltage                  | —    | 0.8  | 1.3  | V     | $T_J = 25^\circ\text{C}, I_S = 76A, V_{GS} = 0V$ ④             |
| $t_{rr}$ | Reverse Recovery Time                  | —    | 80   | 120  | ns    | $T_J = 25^\circ\text{C}, I_F = 76A, V_{DS} = 16V$              |
| $Q_{rr}$ | Reverse Recovery Charge                | —    | 185  | 275  | nC    | $di/dt = 100A/\mu s$ ④                                         |



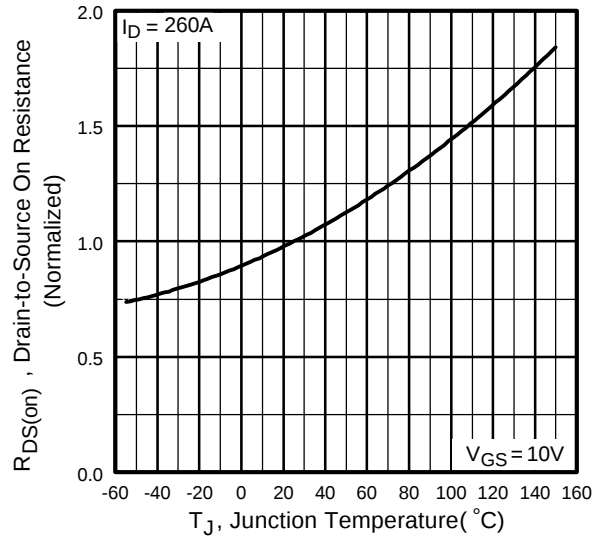
**Fig 1.** Typical Output Characteristics



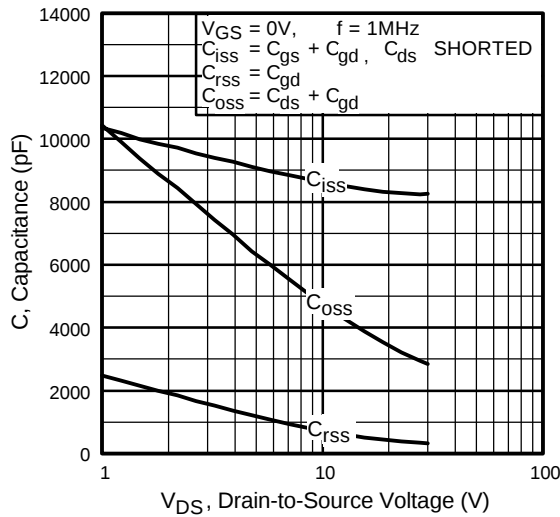
**Fig 2.** Typical Output Characteristics



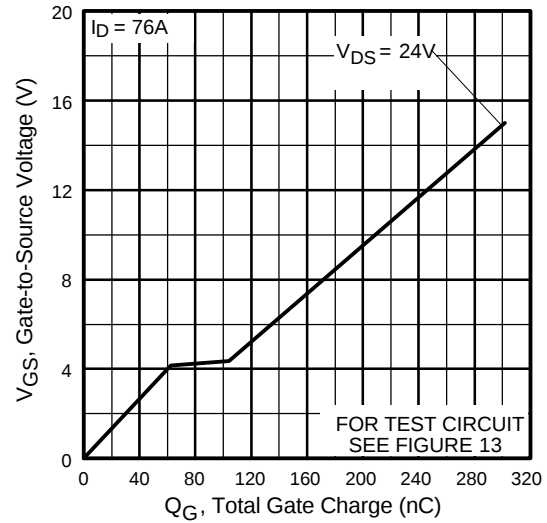
**Fig 3.** Typical Transfer Characteristics



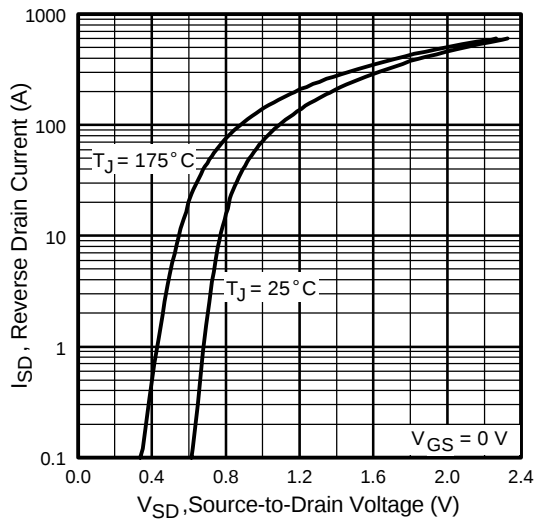
**Fig 4.** Normalized On-Resistance Vs. Temperature



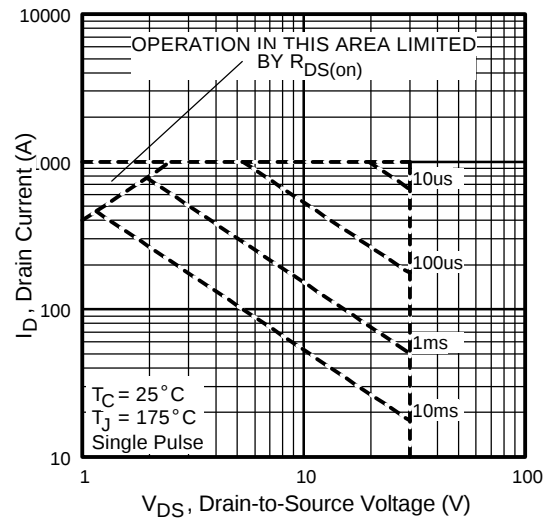
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



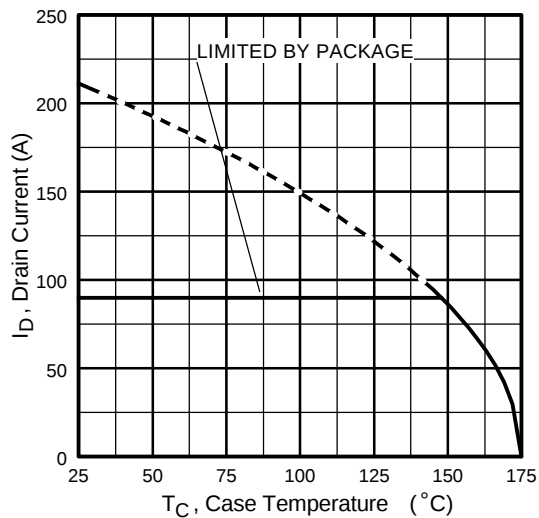
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage



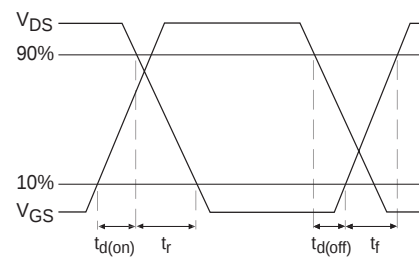
**Fig 8.** Maximum Safe Operating Area



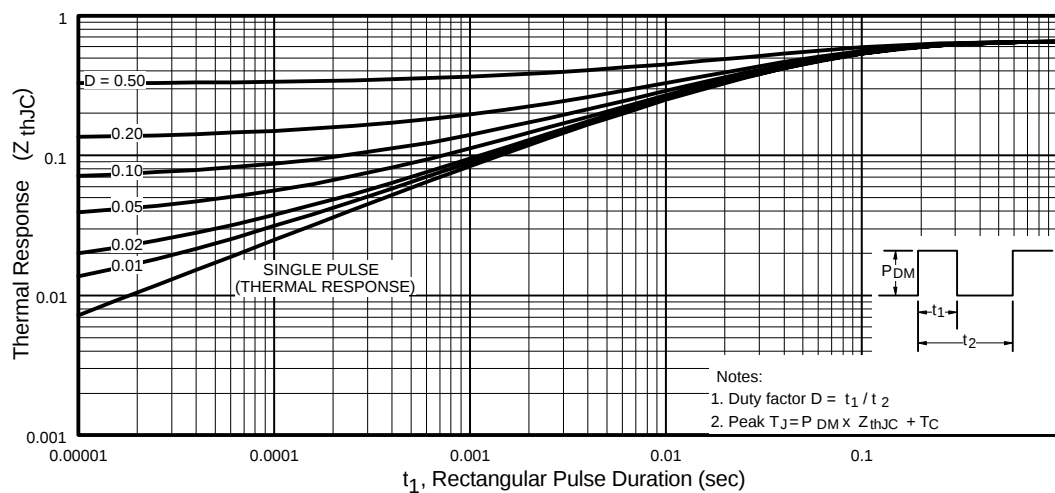
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



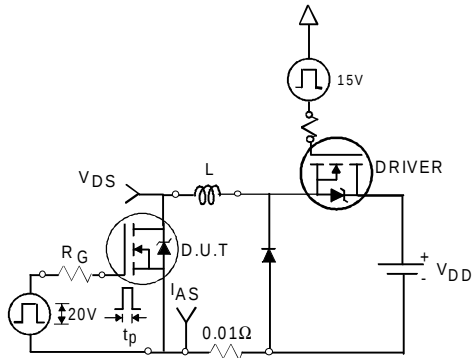
**Fig 10b.** Switching Time Waveforms



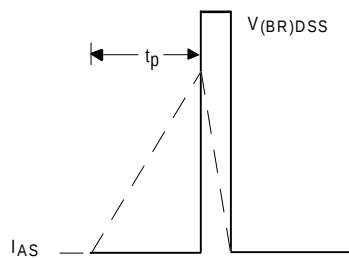
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

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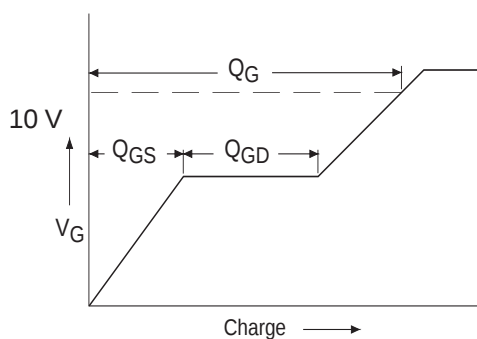
International  
**IR** Rectifier



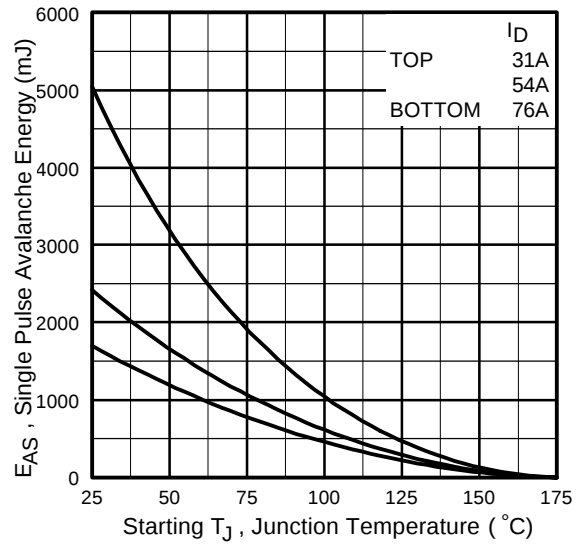
**Fig 12a.** Unclamped Inductive Test Circuit



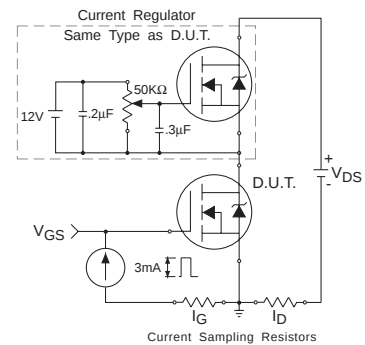
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 13a.** Basic Gate Charge Waveform

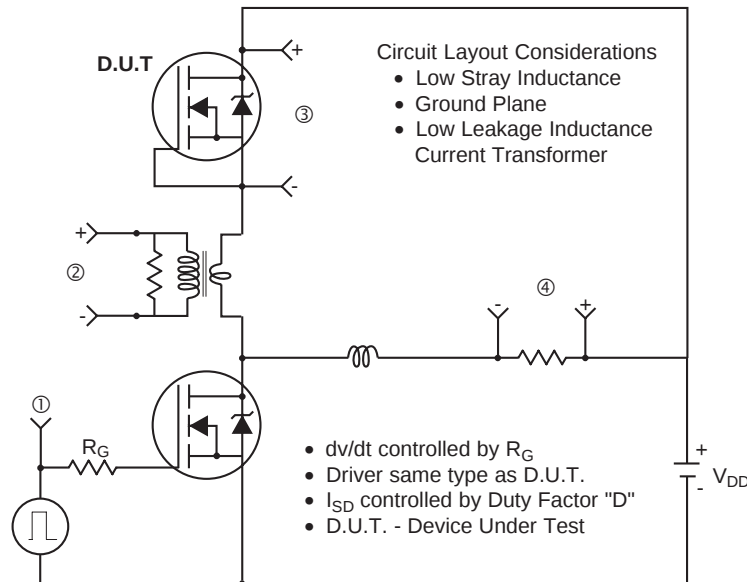


**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 13b.** Gate Charge Test Circuit

### Peak Diode Recovery dv/dt Test Circuit



\*  $V_{GS} = 5V$  for Logic Level Devices

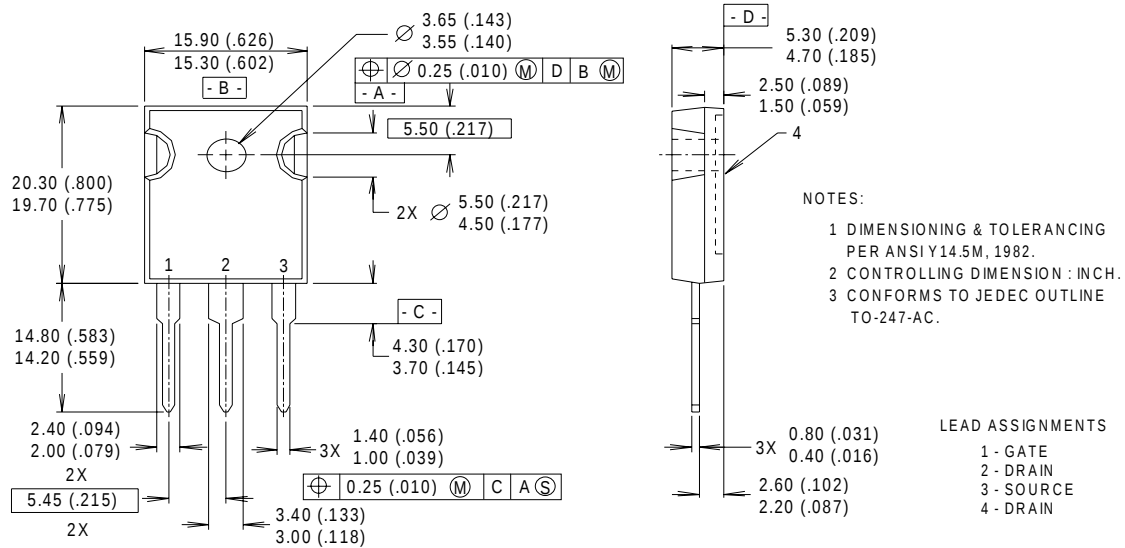
**Fig 14.** For N-Channel HEXFET® Power MOSFET

# IRFP3703

International  
**IR** Rectifier

## TO - 247 Package Outline

Dimensions are shown in millimeters (inches)



### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.6\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 76\text{A}$ .
- ③  $I_{SD} \leq 76\text{A}$ ,  $di/dt \leq 100\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  
 $T_J \leq 175^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ⑤  $C_{OSS}$  eff. is a fixed capacitance that gives the same charging time as  $C_{OSS}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$
- ⑥ Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 90A

International  
**IR** Rectifier

**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
**IR EUROPEAN REGIONAL CENTRE:** 439/445 Godstone Rd, Whyteleafe, Surrey CR3 0BL, UK Tel: ++ 44 (0)20 8645 8000  
**IR CANADA:** 15 Lincoln Court, Brampton, Ontario L6T3Z2, Tel: (905) 453 2200  
**IR GERMANY:** Saalburgstrasse 157, 61350 Bad Homburg Tel: ++ 49 (0) 6172 96590  
**IR ITALY:** Via Liguria 49, 10071 Borgaro, Torino Tel: ++ 39 011 451 0111  
**IR JAPAN:** K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo 171 Tel: 81 (0)3 3983 0086  
**IR SOUTHEAST ASIA:** 1 Kim Seng Promenade, Great World City West Tower, 13-11, Singapore 237994 Tel: ++ 65 (0)838 4630  
**IR TAIWAN:** 16 Fl. Suite D. 207, Sec. 2, Tun Haw South Road, Taipei, 10673 Tel: 886-(0)2 2377 9936  
*Data and specifications subject to change without notice. 6/00*